

What is claimed is:

1. A ceramic packaging method employing a flip-chip bonding, comprising the steps of:

5 (a) forming a gold bump on a chip bond pad in a wafer;
(b) dividing the wafer into a plurality of chips by a die sawing;

(c) aligning a Cu pattern and the gold bump on a ceramic package and adhering a bottom chip to the ceramic package through the Cu pattern and the gold bump;
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(d) adhering a top chip to the bottom chip by using an adhesive, thereby forming a bottom/top chip structure of the bottom and top chip;

(e) electrically connecting the chip bond pad to the bottom chip and the chip bond pad to the top chip by interconnecting the bottom and the top chips; and
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(f) encapsulating interconnected portions of the bottom and the top chips.

20 2. The method of claim 1, wherein a heat emitter is installed on a bottom portion of the ceramic package in order to emit heat generated from the bottom and the top chip.

25 3. The method of claim 1, wherein a groove is formed on the Cu pattern so that the gold bump is safely attached

thereto.

4. The method of claim 1, wherein the adhesive is an epoxy or a polyimide tape.

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5. The method of claim 1, wherein a flip-chip bonding is carried out with respect to the top chip.

6. The method of claim 1, wherein the bottom and the top
10 chip are electrically interconnected to each other by the Cu pattern.

7. The method of claim 1, wherein the interconnected portions are encapsulated by an epoxy resin.

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